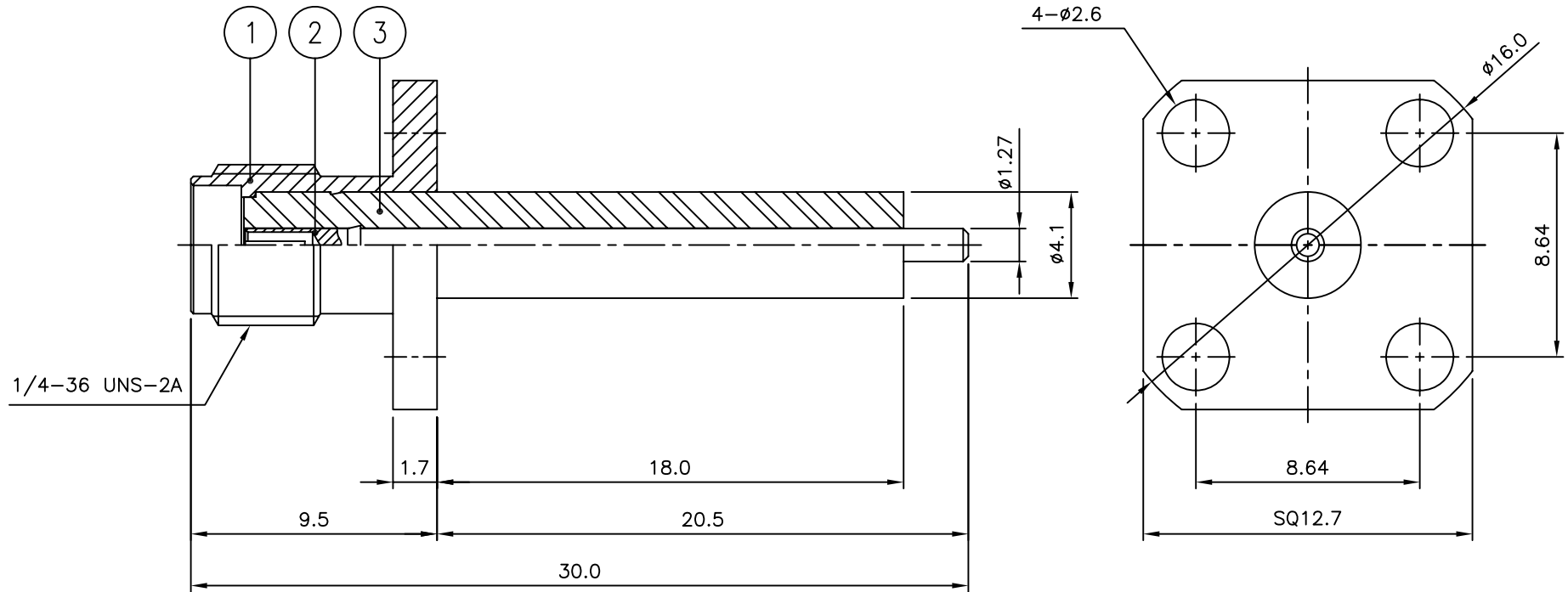


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	C.K.KIM	I.C.KIM	2016.11.23.



조립순서

1. ①번 BODY에 ②번 TEFLON을 조립한다.
2. ③번 PIN을 조립한다.

*PIN의 경우 HAND PRESS 높이 조절 Setting 후 조립 할 것.

3	INSULATOR	1	TEFLON		DIN02850-N/2
2	CONTACT	1	BeCu C17300	Gold Plate	DCT03785-5/2
1	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD03576-5/2
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2016. 11. 23.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE SMA50 SOLDER END JS-4H
		DRAWN BY	C.K.KIM	
FINISH		SCALE	4/1	A4 DWG NO. CN03174-7/3 REVISION I R SHEET 1 of 1
		UNIT	mm	